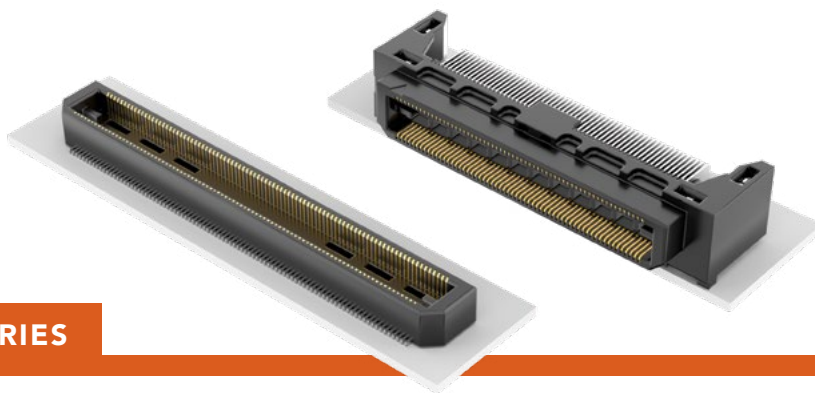


BASIC BLADE & BEAM HEADER

(0.50 mm) .0197" PITCH • BTH SERIES



BTH
Mates:
BSH

SPECIFICATIONS

Insulator Material:

Black LCP

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over
50 μ " (1.27 μ m) Ni

Current Rating:

2.0 A per pin
(2 pins powered)

Operating Temp Range:

-55 $^{\circ}$ C to +125 $^{\circ}$ C

Voltage Rating:

175 VAC

Max Cycles:

100

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

Vertical=
(0.10 mm) .004" max (030-090),
(0.15 mm) .006" max (120-150)*
Right-angle=
(0.15 mm) .006" max (030-090)*
*(.004" stencil solution
may be available; contact
IPG@samtec.com)

Board Stacking:
For applications requiring more
than two connectors per board
or 90 positions or higher,
contact ipg@samtec.com

Board Stacking:

For applications requiring more
than two connectors per board
or 90 positions or higher,
contact ipg@samtec.com

BTH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
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-030, -050, -060,
-090, -120, -150

-F
= Gold Flash
on contact,
Matte Tin on tail

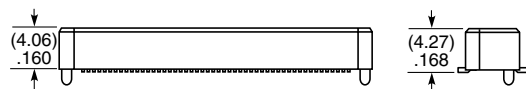
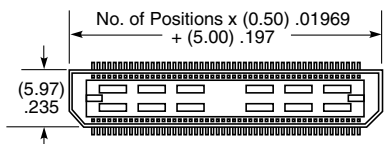
-L
= 10 μ " (0.25 μ m)
Gold on contact,
Matte Tin on tail

-C*
= Electro-Polished Selective
50 μ " (1.27 μ m) min
Au over 150 μ " (3.81 μ m)
Ni on Signal Pins in contact
area, Matte Tin over
50 μ " (1.27 μ m) min
Ni on all solder tails
(*C Plating passes
10 year MFG testing)

-K
= (7.00 mm) .276"
DIA Polyimide
Film Pick
& Place Pad

-TR
= Tape & Reel
(120 positions
maximum)

-FR
= Full Reel
Tape & Reel
(must order
maximum
quantity
per reel;
contact
Samtec for
quantity breaks)
(120 positions
maximum)



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00 mm) .1971"

*Processing conditions
will affect mated height.

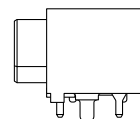
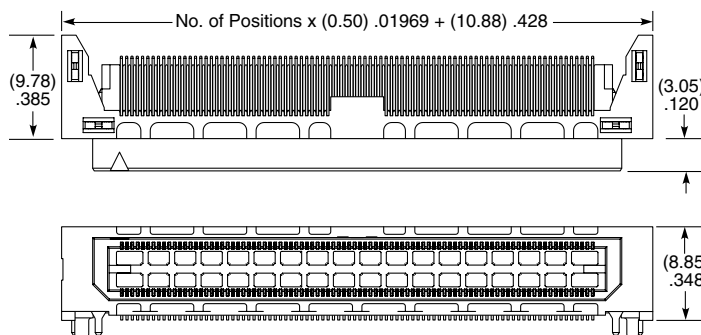
BTH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	RA	WT	OTHER OPTION
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-030, -060, -090

-F
= Gold Flash on
contact, Matte
Tin on tail

-L
= 10 μ " (0.25 μ m)
Gold on contact,
Matte Tin on tail

-K
= (7.00 mm)
.276" DIA
Polyimide
Film Pick &
Place Pad



ALSO AVAILABLE

MOQ Required

30 μ " (0.76 μ m) Gold
Edge Mount Capability
8 mm, 11 mm, 16 mm,
19 mm and 22 mm Stack
Height (Caution: Some
automatic placement/
inspection machines may
have component height
restrictions. Please consult
machinery specifications.)
(11 mm, 16 mm, 19 mm
and 22 mm not available
with 50 positions)



Note:
Some lengths, styles and
options are non-standard,
non-returnable.